

CLAIMS

[1] A module comprising:
a substrate; and
a plurality of semiconductor packages, each comprising a
5 semiconductor chip, mounted on the substrate;
wherein each of the plurality of semiconductor packages comprises a
first radio communication element for transmitting and receiving a signal
between the semiconductor chips in the plurality of semiconductor packages
by radio communication, and
10 the first radio communication element is constituted independently of
the semiconductor chip.

[2] The module according to claim 1, wherein each of the plurality of
semiconductor packages further comprises a resin portion for sealing the
semiconductor chip.

15 [3] The module according to claim 1, wherein each of the plurality of
semiconductor packages further comprises a resin portion for sealing the
semiconductor chip, and
the first radio communication element is provided inside or on a
surface of the resin portion.

20 [4] The module according to claim 1, wherein each of the plurality of
semiconductor packages further comprises a shielding layer for blocking an
electromagnetic wave.

25 [5] The module according to claim 1, wherein each of the plurality of
semiconductor packages further comprises a shielding layer for blocking an
electromagnetic wave in a part of a surface of the first radio communication
element.

[6] The module according to claim 1, wherein each of the plurality of
semiconductor packages further comprises an interposer on which the
semiconductor chip is placed.

30 [7] The module according to claim 1, wherein each of the plurality of

semiconductor packages further comprises an interposer on which the semiconductor chip is placed, and

the first radio communication element is provided inside or on a surface of the interposer.

5 [8] The module according to claim 1, wherein the substrate is a single-sided substrate obtained by forming a conductor pattern on only one principal surface of a base or a double-sided substrate obtained by forming a conductor pattern on both principal surfaces of the base, and

10 each of the plurality of semiconductor packages is mounted on the conductor pattern.

[9] The module according to claim 8, wherein the conductor pattern is constituted by at least one terminal selected from the group consisting of a power source terminal and a ground terminal.

[10] The module according to claim 1, further comprising a second radio communication element for transmitting and receiving a signal with respect to at least one of the first radio communication elements included respectively in the plurality of semiconductor packages by radio communication, and an electronic component electrically connected to the second radio communication element.

20 [11] A mounted structure comprising the module according to claim 1.